

L Number	Hits	Search Text	DB	Time stamp
1	369511	wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 10:16
2	1276	(alignment align aligned aligning) same (scribe with line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 10:17
3	621	wafer same ((alignment align aligned aligning) same (scribe with line))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 10:17
4	188	(through via hole) same (wafer same ((alignment align aligned aligning) same (scribe with line)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 10:20
5	123	(mark point cross position) same ((through via hole) same (wafer same ((alignment align aligned aligning) same (scribe with line))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 11:00
6	12765	wafer with (thru through hole via) with (intersection mark point cross position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 11:01
7	35	(wafer with (thru through hole via) with (intersection mark point cross position)) same ((alignment align aligned aligning) same (scribe with line))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/01 11:01